

Applic. No.: 10/651,856

Amdt. Dated June 30, 2005

Reply to Office action of April 22, 2005

**BEST AVAILABLE COPY**REMARKS/ARGUMENTS

Reconsideration of the application is requested.

Claims 1-29, 31-38, and 40-41 remain in the application.

Claims 31 and 41 have been amended. Claims 30 and 39 have been cancelled. Method claims 1-23 have been previously withdrawn and rejoinder of these claims has been requested.

In the section entitled "Claim Rejections - 35 USC § 112" on page 2 of the above-identified Office action, claims 31-32 and 40-41 have been rejected as being indefinite under 35 U.S.C. § 112, second paragraph.

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More specifically, the Examiner has stated that claims 31 and 40 recite "the active surface being embedded in said first plastic layer" and at least one wiring structure disposed above said second plastic layer, which are supported by Figs. 9-11 of the drawings. Appropriate changes to the language of claims 31 and 40 have been made.

The Examiner has also stated that claim 39 recites an unclear limitation "said wiring structure has an adhesive layer on interfaces to a plastic plate formed by said first and second

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layers" because it is not disclosed in the invention of the instant application. Claim 39 has been cancelled.

It is accordingly believed that the claims meet the requirements of 35 U.S.C. § 112, second paragraph. Should the Examiner find any further objectionable items, counsel would appreciate a telephone call during which the matter may be resolved. The above-noted changes to the claims are provided solely for cosmetic and/or clarificatory reasons. The changes are neither provided for overcoming the prior art nor do they narrow the scope of the claims for any reason related to the statutory requirements for a patent.

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In the section entitled "Claim Rejections - 35 USC § 103" on pages 2-9 of the above-mentioned Office action, claims 24-29 and 31-41 have been rejected as being unpatentable over Jiang et al. (US 6,515,355 B1) in view of Takeuchi et al. (US 6,548,598 B2) under 35 U.S.C. § 103(a).

As will be explained below, it is believed that the claims were patentable over the cited art in their original form and the claims have, therefore, not been amended to overcome the references.

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Before discussing the prior art in detail, it is believed that a brief review of the invention as claimed, would be helpful.

Claims 24 and 31 call for, inter alia:

a multilayer plastic embedding compound embedding the semiconductor chip, said multilayer compound forming a first plastic layer and a second plastic layer;

...

said first plastic layer having a bead surrounding the semiconductor chip.

Claims 33 and 40 call for, inter alia:

said first plastic layer having a bead surrounding the semiconductor chip;

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at least one of said first and second plastic layers being at least partly cured and forming a self-supporting, substantially dimensionally stable, multilayer plastic plate.

With regard to the Examiner's comments in the fourth paragraph on page 9 of the Office action, it is noted that although an FR4 board and siloxane are plastic, a person skilled in the art would not consider them as a "plastic embedding compound" in the sense of the invention of the instant application. A person skilled in the art would not regard the phrase "plastic embedding compound" as including the BT or FR4 substrate as taught by Jiang et al.

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Further, Applicants maintain that the feature "said first plastic layer having a bead surrounding the semiconductor chip" is not disclosed by Jiang et al. or Takeuchi et al.

Takeuchi et al. teach a thermoplastic resin composition which may include a filler that can contain glass beads. However, although Takeuchi et al. teach a filler material which includes glass beads, they fail to teach a bead that surrounds, or is capable of surrounding, a semiconductor chip. The electronic component of the invention of the instant application is, therefore, not provided by a simple combination of the teaching of Jiang et al. and Takeuchi et al.

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As already discussed in the previous response, none of the cited references give a person skilled in the art any incentive to provide an electronic component which includes a first and a second plastic embedding compound and in which the first plastic layer includes a bead which surrounds the semiconductor chip.

It is accordingly believed to be clear that none of the references, whether taken alone or in any combination, either show or suggest the features of claims 24, 31, 33, and 40. Claim 24, 31, 33, and 40 are, therefore, believed to be

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patentable over the art and since all of the dependent claims are ultimately dependent on claims 24 and 33, they are believed to be patentable as well.

In view of the foregoing, reconsideration and allowance of claims 24-29, 31-38, and 40-41 are solicited. Rejoinder of method claims 1-23 is requested upon allowance of product claims under MPEP 821.04 ("if applicant elects claims directed to the product, and a product claim is subsequently found allowable, withdrawn process claims which depend from or otherwise include all the limitations of the allowable product claim will be rejoined").

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In the event the Examiner should still find any of the claims to be unpatentable, counsel would appreciate a telephone call so that, if possible, patentable language can be worked out. In the alternative, the entry of the amendment is requested as it is believed to place the application in better condition for appeal, without requiring extension of the field of search.

If an extension of time for this paper is required, petition for extension is herewith made. Please charge any fees which might be due with respect to 37 CFR Sections 1.16 and 1.17 to

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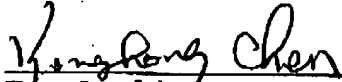
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the Deposit Account of Lerner and Greenberg, P.A., No. 12-  
1099.

Respectfully submitted,

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For Applicants

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